

# HiPerFET™ Power MOSFETs

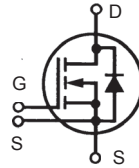
## IXFN 32N120

$$V_{DSS} = 1200V$$

$$I_{D25} = 32A$$

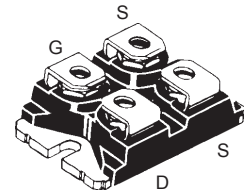
$$R_{DS(on)} = 0.35\Omega$$

N-Channel Enhancement Mode  
Avalanche Rated, High dv/dt, Low  $t_{rr}$



Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ C$ to $150^\circ C$	1200	V
$V_{DGR}$	$T_J = 25^\circ C$ to $150^\circ C$ ; $R_{GS} = 1 M\Omega$	1200	V
$V_{GS}$	Continuous	$\pm 30$	V
$V_{GSM}$	Transient	$\pm 40$	V
$I_{D25}$	$T_C = 25^\circ C$ , Chip capability	32	A
$I_{DM}$	$T_C = 25^\circ C$ , pulse width limited by $T_{JM}$	128	A
$I_{AR}$	$T_C = 25^\circ C$	32	A
$E_{AR}$	$T_C = 25^\circ C$	64	mJ
$E_{AS}$	$T_C = 25^\circ C$	4	J
<b>dv/dt</b>	$I_S \leq I_{DM}$ , $di/dt \leq 100 A/\mu s$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ C$ , $R_G = 2 \Omega$	15	V/ns
$P_D$	$T_C = 25^\circ C$	780	W
$T_J$		-55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		-55 ... +150	$^\circ C$
$V_{ISOL}$	50/60 Hz, RMS $t = 1$ min $I_{ISOL} \leq 1$ mA $t = 1$ s	2500 3000	V~ V~
$M_d$	Mounting torque Terminal connection torque	1.5/13 1.5/13	Nm/lb.in. Nm/lb.in.
<b>Weight</b>		30	g

miniBLOC, SOT-227 B (IXFN)  
E153432



G = Gate  
S = Source  
D = Drain  
TAB = Drain

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

### Features

- International standard package
- miniBLOC, with Aluminium nitride isolation
- Low  $R_{DS(on)}$  HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic Rectifier

### Applications

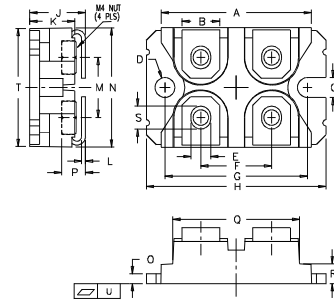
- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls

### Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ C$ , unless otherwise specified)		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = 0 V$ , $I_D = 3$ mA	1200		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 8$ mA	2.5		V
$I_{GSS}$	$V_{GS(th)} = \pm 30 V_{DC}$ , $V_{DS} = 0$			$\pm 200$ nA
$I_{DSS}$	$V_{DS} = V_{DSS}$ , $V_{GS} = 0 V$		$T_J = 25^\circ C$ $T_J = 125^\circ C$	50 $\mu A$ 3 mA
$R_{DS(on)}$	$V_{GS} = 10 V$ , $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300 \mu s$ , duty cycle $d \leq 2\%$			0.35 $\Omega$

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$g_{fs}$	$V_{DS} = 20\text{ V}; I_D = 0.5 \cdot I_{D25}$ , pulse test	28	52	S
$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		15900	pF
$C_{oss}$			1000	pF
$C_{rss}$			260	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1\ \Omega$ (External),		36	ns
$t_r$			42	ns
$t_{d(off)}$			98	ns
$t_f$			22	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$		400	nC
$Q_{gs}$			70	nC
$Q_{gd}$			188	nC
$R_{thJC}$			0.16	K/W
$R_{thCK}$		0.05		K/W

**miniBLOC, SOT-227 B**


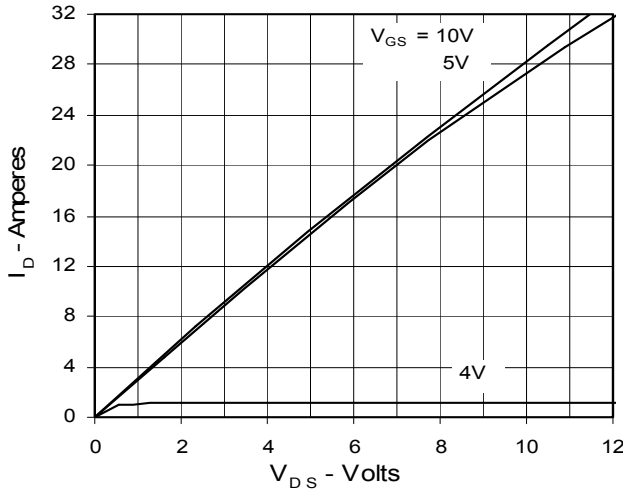
M4 screws (4x) supplied

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	38.00	38.23	1.496	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004

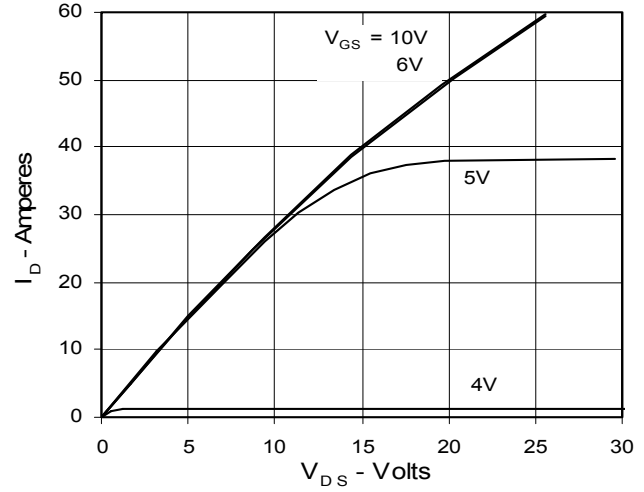
Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$I_S$	$V_{GS} = 0\text{ V}$			32 A
$I_{SM}$	Repetitive; pulse width limited by $T_{JM}$			128 A
$V_{SD}$	$I_F = I_S, V_{GS} = 0\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$			1.3 V
$t_{rr}$	$I_F = 25\text{ A}, -di/dt = 100\text{ A}/\mu\text{s}, V_R = 100\text{ V}$		180	300 ns
$Q_{RM}$			1.4	$\mu\text{C}$
$I_{RM}$			8	A

IXYS reserves the right to change limits, test conditions, and dimensions.

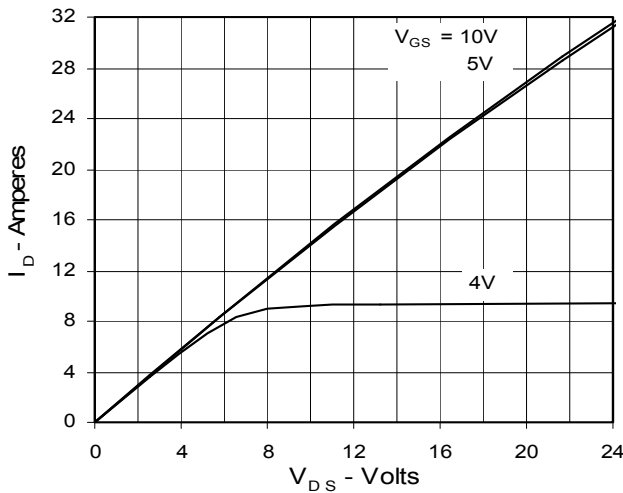
**Fig. 1. Output Characteristics @ 25 Deg. C**



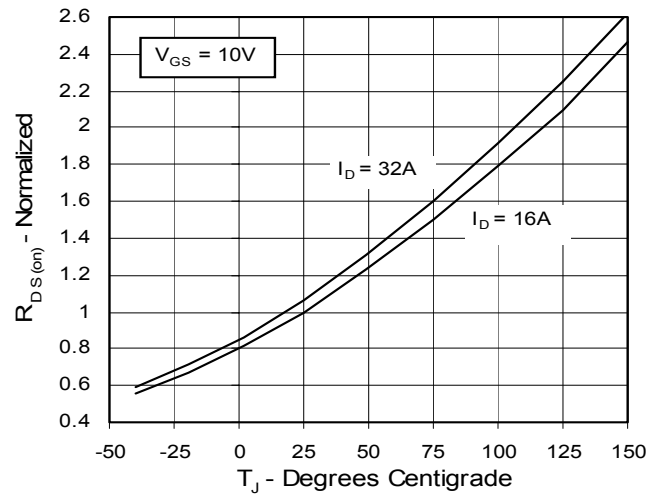
**Fig. 2. Extended Output Characteristics @ 25 deg. C**



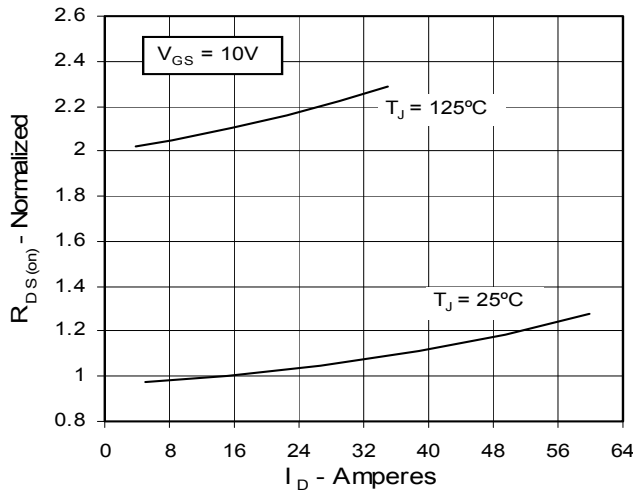
**Fig. 3. Output Characteristics @ 125 Deg. C**



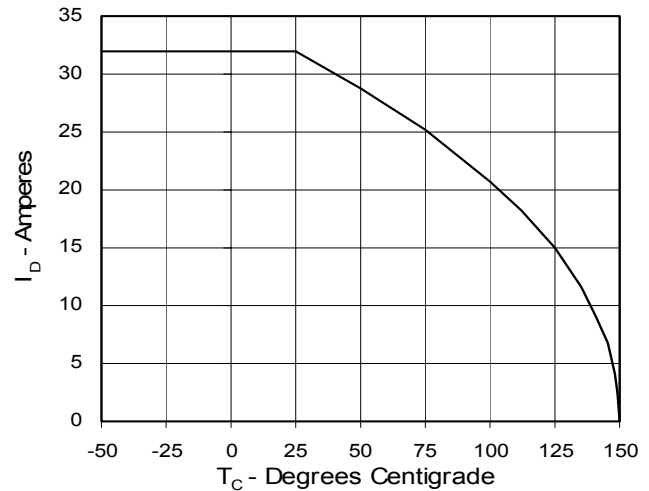
**Fig. 4. R\_DS(on) Normalized to I\_D25 Value vs. Junction Temperature**



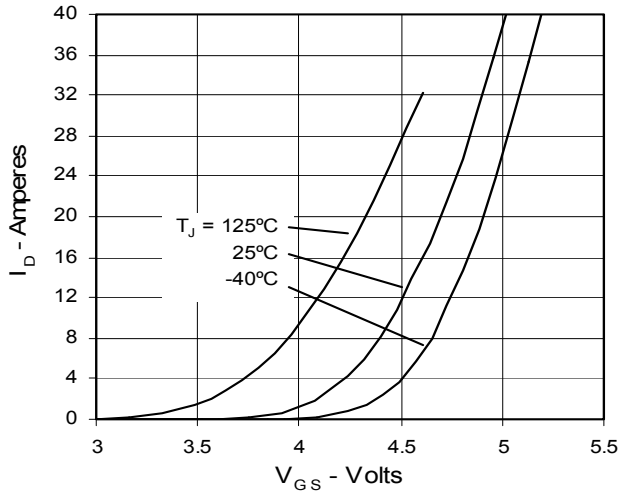
**Fig. 5. R\_DS(on) Normalized to I\_D25 Value vs. I\_D**



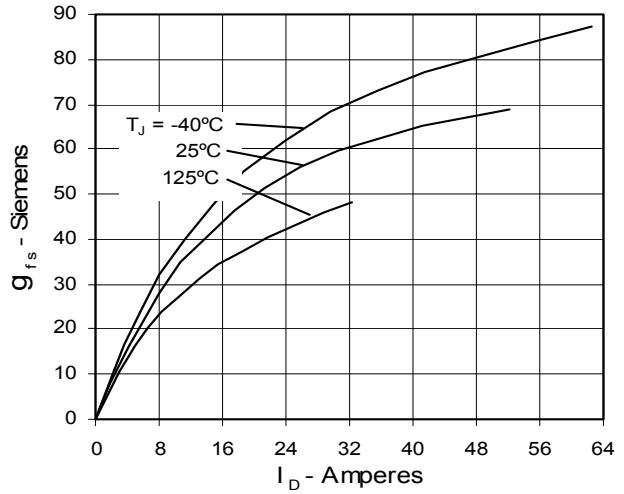
**Fig. 6. Drain Current vs. Case Temperature**



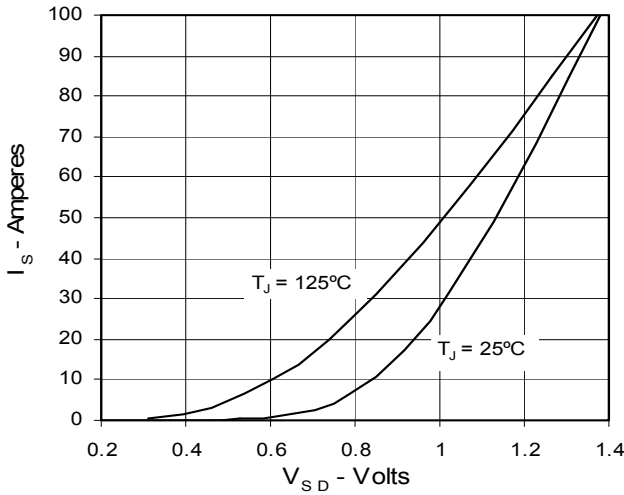
**Fig. 7. Input Admittance**



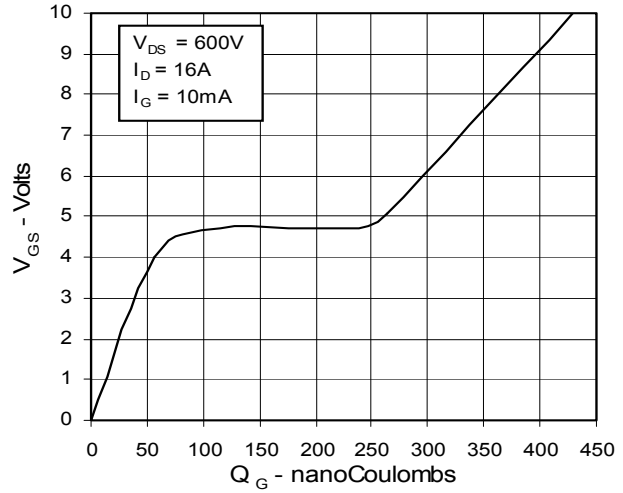
**Fig. 8. Transconductance**



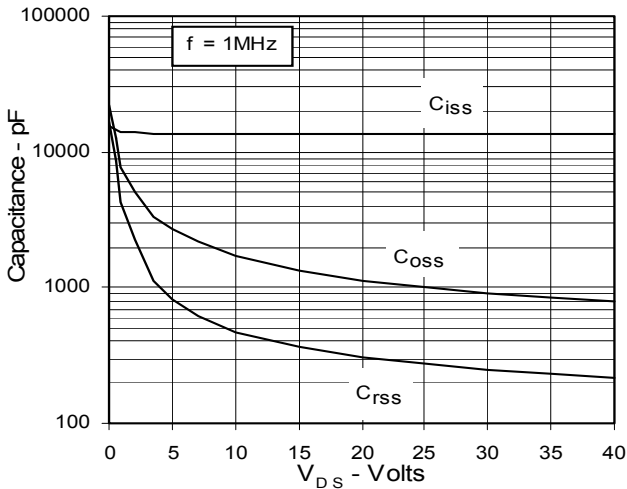
**Fig. 9. Source Current vs. Source-To-Drain Voltage**



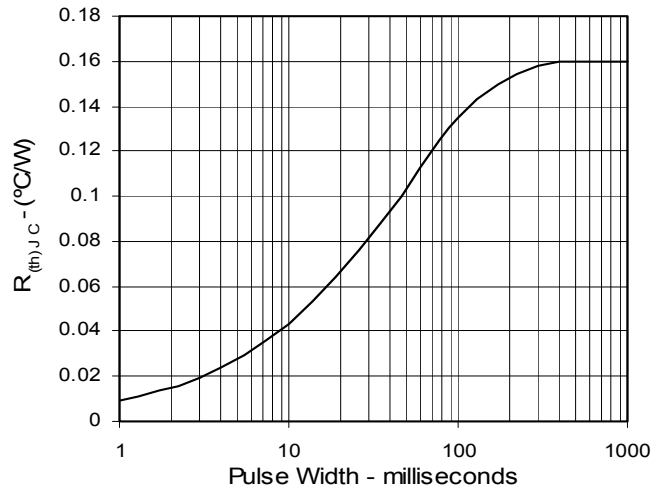
**Fig. 10. Gate Charge**



**Fig. 11. Capacitance**



**Fig. 12. Maximum Transient Thermal Resistance**



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